



ADAT3XF PiXelect MiniLED Bonder

Application

- High Speed High Accuracy MiniLED Bonder with flipchip function

Key Feature

- Running 70000 units per hour
- Able to handle smallest LED sizes in the market
- Flip and non-flip configuration at same speed
- Standard deviation x/y position better than 3µm
- Handles Sorted as well as EPI wafer input (sorting & bonding integrated)
- 100% high resolution optical inspections on die, attach and post-bond steps without compromising on machine speed
- 8" FFC ring with fully automatic waferchange
- Can be configured for manual load as well as conveyor belt interface with a series of systems (RGB line)
- Can handle R, G, B colors in single machine with placement gap down to 20µm